

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	570	257/\$.ccls. and conductive adj2 (area strip line) and (substrate wafer board) with (p-type n-type) same well	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:38	
2	BRS	L2	1578	257/\$.ccls. and conductive adj2 (area strip line) and (substrate wafer board) with (p-type n-type)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:39	
3	BRS	L3	185	257/\$.ccls. and conductive adj2 (area strip line) and (substrate wafer board) same p-n adj junction	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:43	
4	BRS	L4	83	438/\$.ccls. and conductive adj2 (area strip line) and (substrate wafer board) same p-n adj junction	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:48	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	11	"5916715"	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:46	
6	BRS	L6	8	("3751647"   "3842491"   "5553274"   "5705301"   "5707765"   "5723233"   "5773315"   "5861679") .PN.	USPA T	2004/08/0 6 19:47	
7	BRS	L7	6	361/.ccls. and conductive adj2 (area strip line) and (substrate wafer board) same p-n adj junction	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/08/0 6 19:48	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	220	257/\$.ccls. and p-n adj junction same (substrate wafer board) and metal adj (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM _TDB	2004/08/0 7 17:41	
2	BRS	L2	116	438/\$.ccls. and p-n adj junction same (substrate wafer board) and metal adj (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM _TDB	2004/08/0 7 17:10	
3	BRS	L3	2	361/\$.ccls. and p-n adj junction same (substrate wafer board) and metal adj (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM _TDB	2004/08/0 7 17:12	
4	BRS	L4	1	174/\$.ccls. and p-n adj junction same (substrate wafer board) and metal adj (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM _TDB	2004/08/0 7 17:13	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	24	257/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material with (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/08/0 7 17:25	
6	BRS	L6	18	438/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material with (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/08/0 7 17:24	
7	BRS	L7	0	361/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material with (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/08/0 7 17:24	
8	BRS	L8	0	174/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material with (strip line area)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/08/0 7 17:25	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	L9	413	257/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM_TDB	2004/08/07 17:34	
10	BRS	L10	259	438/.ccls. and p-n adj junction same (substrate wafer board) and dop\$3 adj material	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM_TDB	2004/08/07 17:36	
11	BRS	L11	489	257/653	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM_TDB	2004/08/07 17:36	
12	BRS	L12	1028	257/.ccls. and p-type same n-type same (substrate wafer board) and metal adj (strip line area)	USPAT; US-P GPUB; EPO; JPO; DERW ENT; IBM_TDB	2004/08/07 17:42	